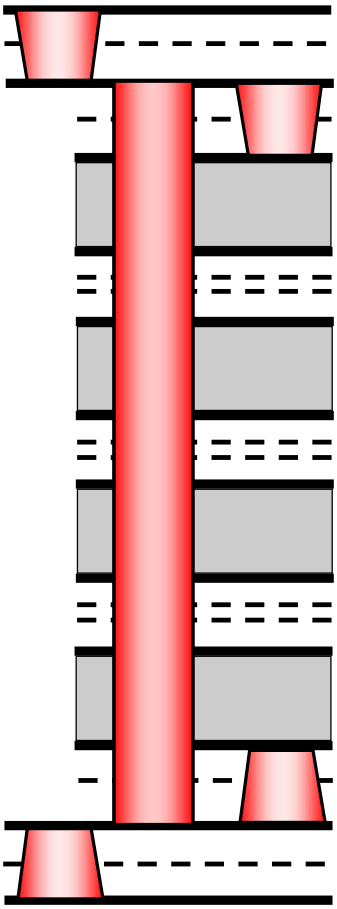
Build Up HDI (Standard)

HDI12_2+8(10b)+2_1,55_35_engl

12 - Layers

Core: 0,15 mm Cu 35/35 µm

WE-Articel No.:	**2 + 8(10B) + 2**
Customer:	



layer description		Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE				[µm]	[µm]
	TOP/VS	Foil	12 µm	1)	12	
				1 x 1080	60	
	2	Foil	9 µm		30	
				1 x 1080	60	
	3		35 µm		33	
		0,150 mm			150	
	4		35 µm		33	
				2 x 1080	124	
	5		35 µm		33	
		0,150 mm			150	
	6		35 µm		33	
				2 x 1080	124	
	7		35 µm		33	
		0,150 mm			150	
	8		35 µm		33	
				2 x 1080	124	
	9		35 µm		33	
		0,150 mm			150	
	10		35 µm		33	
				1 x 1080	60	
	11	Foil	9 µm		30	
				1 x 1080	60	
	BOT/RS	Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1560

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,55**	+/-	0,13	mm				
thickness with electro plated Cu:	1,64	+/-	0,16	mm				
total thickness with soldermask	1,70	+/-	0,18	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
29.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00	13+